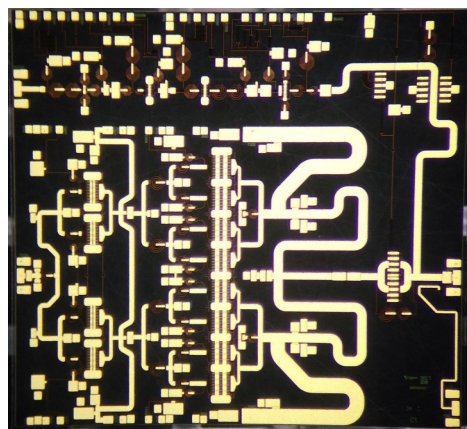


C-Band GaN Single Chip Radar Front End MMIC

Preliminary Datasheet v1

Features

- Integrated single chip front end MMIC incorporating LNA, transmit-receive switch and HPA functions
- Frequency Range: 5.2GHz to 5.6GHz
- Tx (pulsed): Psat 47dBm, >40% PAE typical at TXVd = 30V
- Rx (CW): NF 2.4dB, Gain >35dB typical at RXVd = 7V
- Limited RX output power <12dBm at RXVd = 7V
- Tx/RX switch control voltage (Vswc) between 0V (Tx ON) and -25V (Rx ON)



Description

The VRFC0127-BD is a C-band integrated single chip front end MMIC incorporating a low noise amplifier, a transmit-receive switch and a high power amplifier. The MMIC is designed on a European space qualified process and operates over 5.2GHz to 5.6GHz. The Rx function demonstrates a nominal noise figure of 2.4dB at 5.4GHz with small signal gain greater than 35dB. The Tx function delivers 47dBm at 5.4GHz with a PAE > 40%. The RF ports are DC blocked and matched to 50Ω. Typical applications include satellite communications.

Electrical Specifications

Parameter	Specification			Unit
	Min.	Typ.	Max.	
Frequency Bandwidth	5.2		5.6	GHz
TX Mode (pulsed) $T = 25^{\circ}\text{C}$ baseplate, $V_d = 30\text{V}$, $V_g = -3.3\text{V}$, $\text{Pulse} = 30\mu\text{s}$, $\text{Duty} = 1\%$, $V_{\text{swc}} = 0\text{V}$				
Small Signal Gain		31@5.4GHz		dB
Saturated Output Power		47@5.4GHz		dBm
Power Added Efficiency		>40%		%
I/P Return Loss		-10		dB
RX Mode (CW) $T = 25^{\circ}\text{C}$ baseplate, $V_d = 7\text{V}$, $I_d = 30\text{mA}$, $V_{\text{swc}} = -25\text{V}$				
Small Signal Gain		37@5.4GHz		dB
Noise Figure		2.4@5.4GHz		dB
I/P Return Loss		-10.9@5.4GHz		dB
O/P Return Loss		-24@5.4GHz		dB
P1dB Output Power		9		dBm

VRFC0127-BD

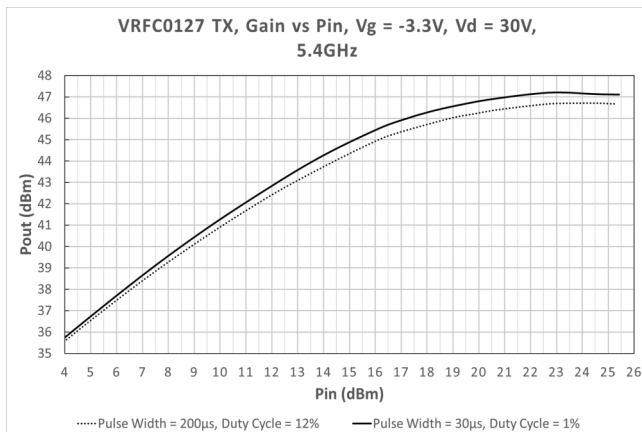


C-Band GaN Single Chip Radar Front End MMIC

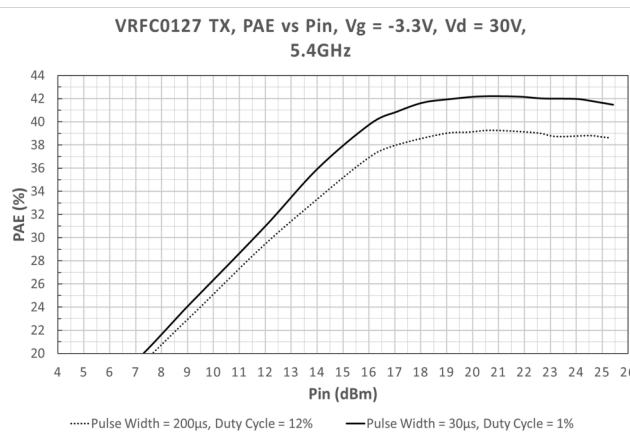
Preliminary Datasheet v1

Measured Performance Tx Mode (in test jig), Vswc = 0V

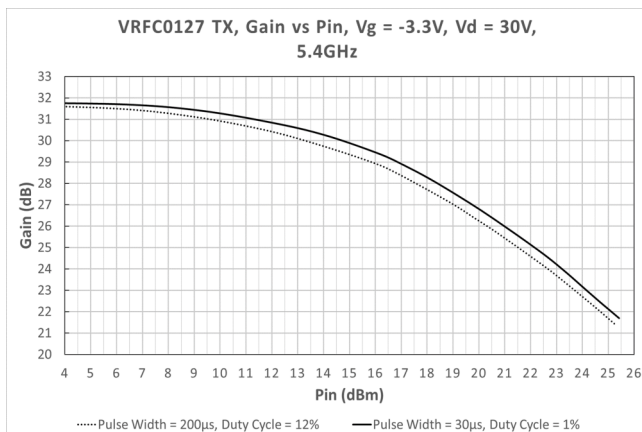
T = 25°C baseplate, Vd = 30V



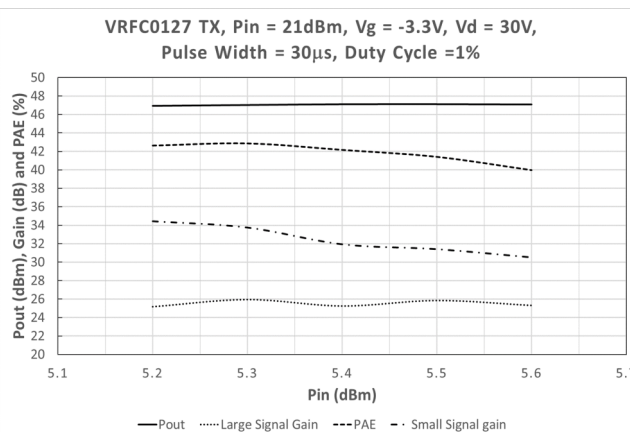
Pout vs. Pin at 5.4GHz as function of duty cycle



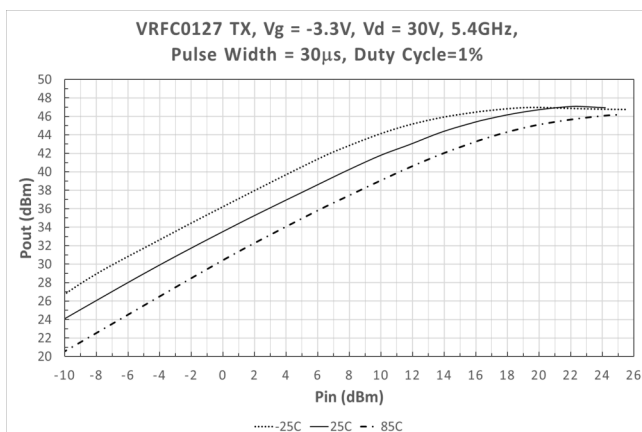
PAE vs. Pin at 5.4GHz as function of duty cycle



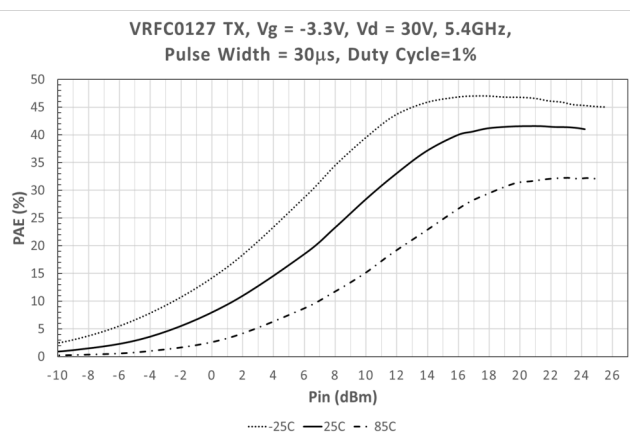
Gain vs. Pin at 5.4GHz as function of duty cycle



Pout, PAE and Gain at Pin=21dBm over frequency



Pout at 5.4GHz at different baseplate temperatures



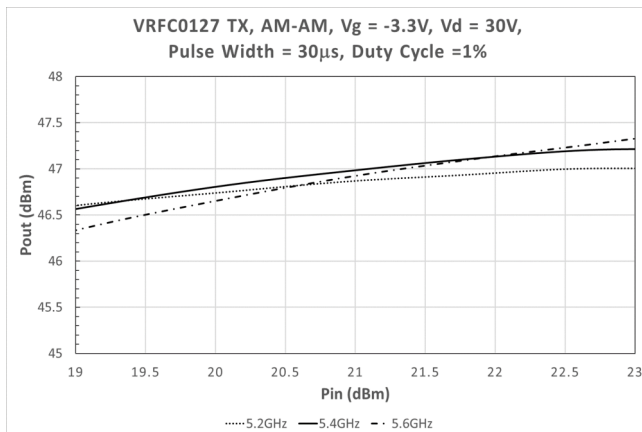
PAE at 5.4GHz at different baseplate temperatures

C-Band GaN Single Chip Radar Front End MMIC

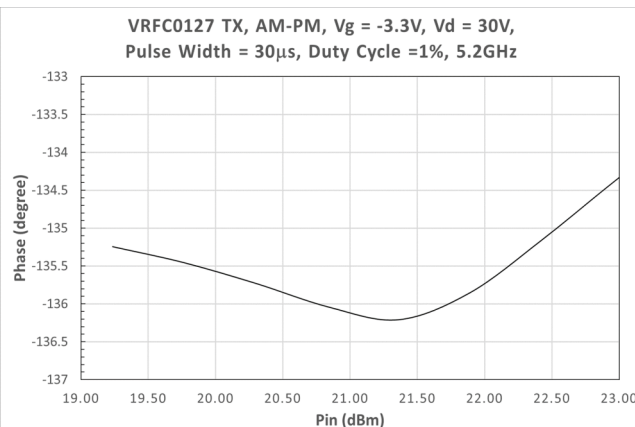
Preliminary Datasheet v1

Measured Performance Tx Mode (in test jig), Vswc = 0V

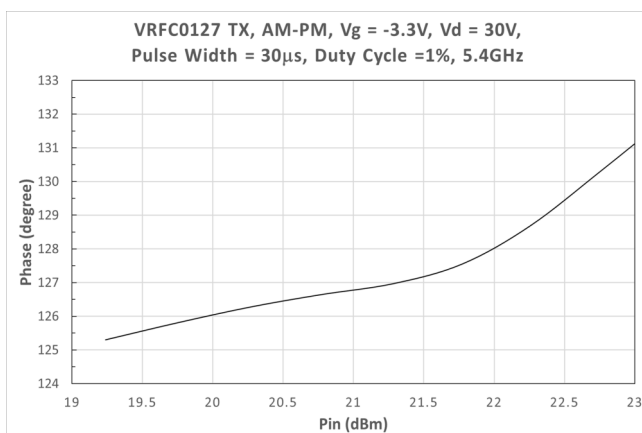
T = 25°C baseplate, Vd = 30V



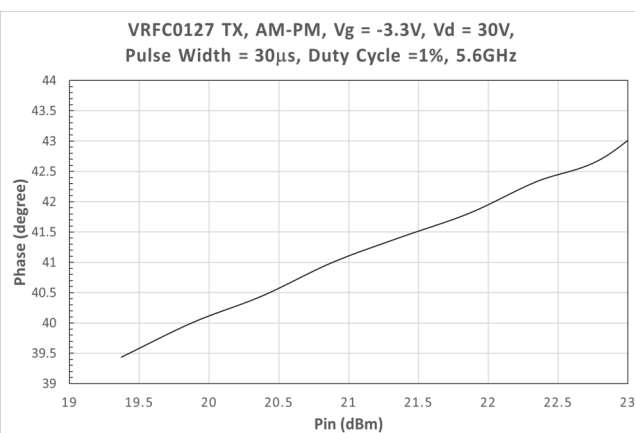
AM-AM Conversion at 5.2GHz, 5.4GHz and 5.6GHz



AM-PM Conversion at 5.2GHz



AM-PM Conversion at 5.4GHz



AM-PM Conversion at 5.6GHz

VRFC0127-BD

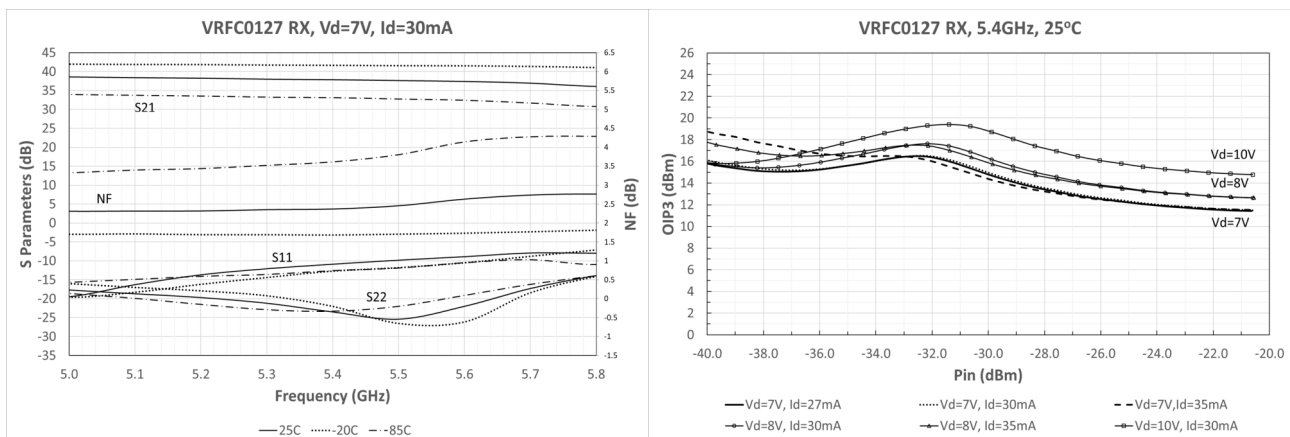
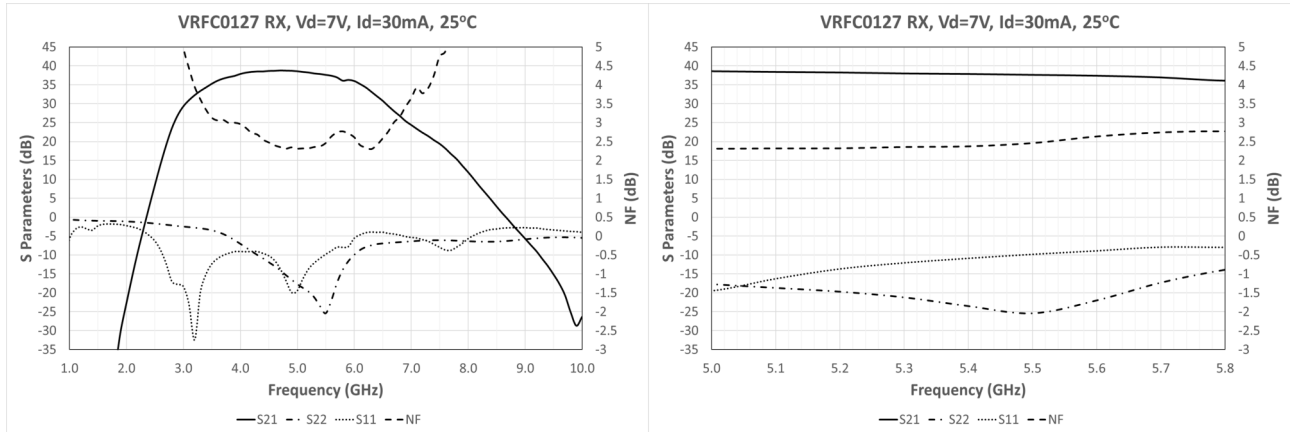


C-Band GaN Single Chip Radar Front End MMIC

Preliminary Datasheet v1

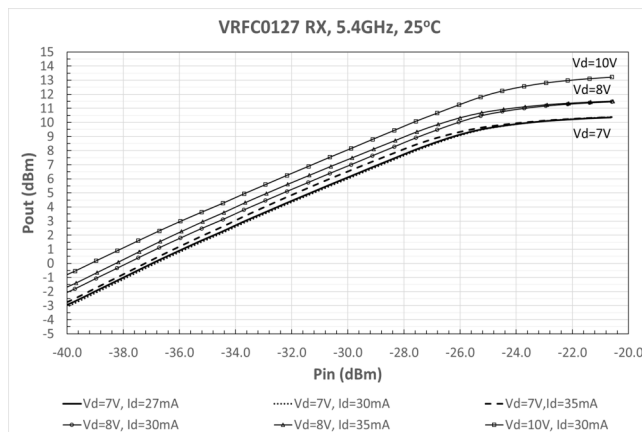
Measured Performance Rx Mode (in test jig), Vswc = -25V

T = 25°C baseplate, Vd = 7V, Id = 30mA



Effect of temperature on small signal

OIP3: Effect of bias conditions at 5.4GHz



Pout: Effect of bias point at 5.4GHz

C-Band GaN Single Chip Radar Front End MMIC

Preliminary Datasheet v1

Recommended Absolute Maximum Ratings ^[1]

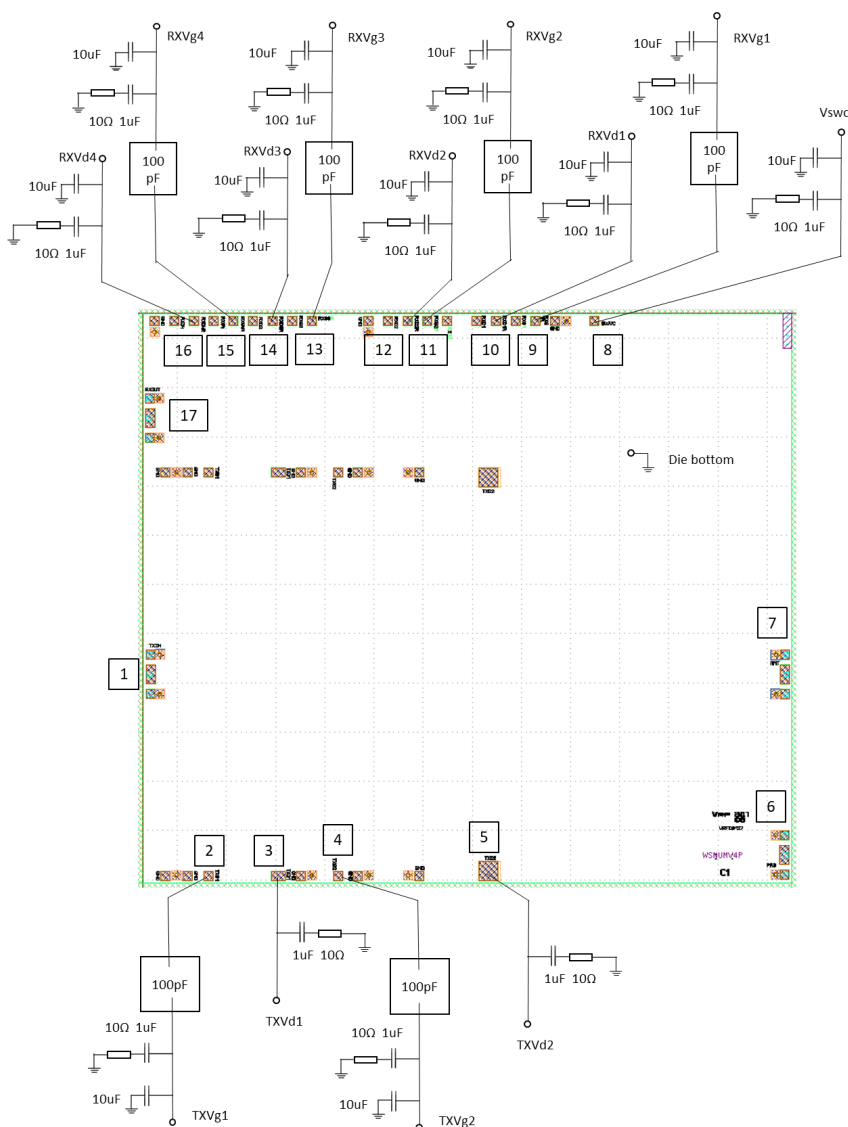
Parameter	Symbol	Value	Notes
Drain bias voltage	Vd	55V	
Gate bias voltage	Vg	-20V	For amplifier gate voltage
Gate bias voltage	Vswc	-60V	For switch control voltage
Gate Current	Ig	5mA	
RF input power	RFin	30dBm/10dBm	For TX input/RX input
Junction Temperature	T _j	160°C/230°C	160°C for space applications/230°C for non-space applications For maximum median device lifetime, T _j should be minimised
Storage Temperature	T _{storage}	-55 to 150°C	

^[1] Operation outside these conditions may cause permanent damage to the device. Combination of maximum rating conditions may reduce the values. Device performance at these ratings is not implied.



Preliminary Datasheet v1

(Please consult VIPER RF if operated in different pulsed conditions)



ID	PAD	NOTE
1	TX IN	
2, 4	TX Gate	Vg=-3.3V typical
3, 5,	TX Drain	Vd=30V typical
6	Sampling	
7	ANT	
8	SW control	Vswc=0V/-25V
9,11,13,15	RX Gate	Vg=-3V typical
10,12,14,16	RX Drain	Vd=7V typical
17	RX OUT	
Die Bottom	GND	

Die Size	5.89mm x 6.7mm
Die Thickness	100μm
Minimum Bondpad opening	100μm x 100μm

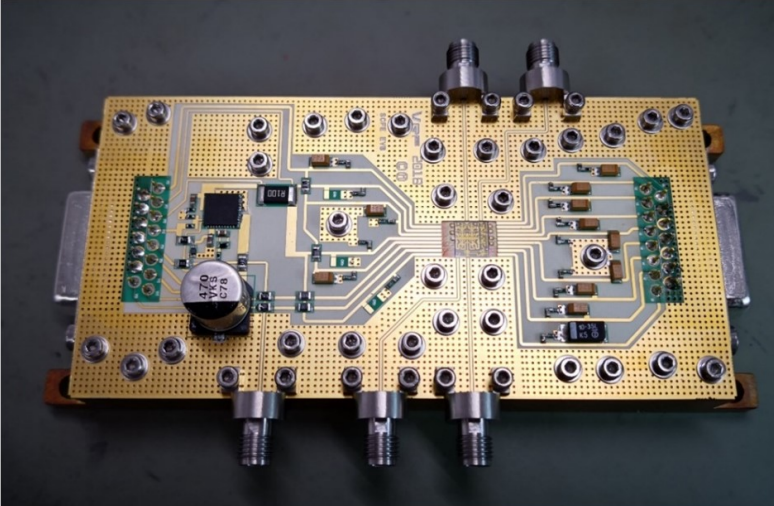
GaN devices are ESD sensitive and precautions should be observed during storage, handling, assembly and testing.



C-Band GaN Single Chip Radar Front End MMIC

Preliminary Datasheet v1

Evaluation Board



Bias Procedure -

Tx Mode Bias-Up:

1. $V_{g\text{-HPA}}$ and $V_{g\text{-LNA}}$ set to -5V.
2. V_{swc} set to 0V.
3. $V_{d\text{-LNA}}$ set to 0V.
4. $V_{d\text{-HPA}}$ set from 0V up to 30V.
5. Adjust $V_{g\text{-HPA}}$ ($V_g = -3.3\text{V}$ Typical).
6. Apply RF signal.

TX Mode Bias-Down:

1. Turn off RF signal.
2. Reduce $V_{g\text{-HPA}}$ to -5V ($I_{d0} \approx 0\text{mA}$).
3. Set $V_{d\text{-HPA}}$ to 0V.
4. Turn off $V_{d\text{-HPA}}$ and $V_{d\text{-LNA}}$.
5. Turn off $V_{g\text{-HPA}}$ and $V_{g\text{-LNA}}$.
6. Turn off V_{swc} .

Rx Mode Bias-Up:

1. $V_{g\text{-LNA}}$ and $V_{g\text{-HPA}}$ set to -5V.
2. V_{swc} set to -25V.
3. $V_{d\text{-HPA}}$ set to 0V.
4. $V_{d\text{-LNA}}$ set from 0V up to 7V.
5. Adjust $V_{g\text{-LNA}}$ until quiescent I_d is 30mA ($V_g = -3\text{V}$ Typical).
6. Apply RF signal.

RX Mode Bias-Down

1. Turn off RF signal.
2. Reduce $V_{g\text{-LNA}}$ to -5V ($I_{d0} \approx 0\text{mA}$).
3. Set $V_{d\text{-LNA}}$ to 0V.
4. Turn off $V_{d\text{-LNA}}$ and $V_{d\text{-HPA}}$.
5. Turn off $V_{g\text{-LNA}}$ and $V_{g\text{-HPA}}$.
6. Turn off V_{swc} .